MBC — X XXX — X X X T

MICRO-D STRAIGHT PCB MOUNT
CONDENSED

GENDER
1 = RECEPTACLE, SOCKET CONTACTS
2 = PLUG, PIN CONTACTS

NUMBER OF CONTACTS
009 025 051
015 031 069
021 037 100

SHELL HARDWARE/BODY STYLE
1 = JACKPOST/BODY STYLE #2
2 = LOW PROFILE HEX JACSKCREW/ BODY STYLE #1
3 = JACKPOST/BODY STYLE #1
4 = FLOAT MOUNT/BODY STYLE #1
5 = NO HARDWARE/BODY STYLE #1
6 = NO HARDWARE/BODY STYLE #2
7 = HIGH PROFILE HEX JACSKCREW/BODY STYLE #1
8 = LOW PROFILE SLOT JACSKCREW/BODY STYLE #1
9 = HIGH PROFILE SLOT JACSKCREW/BODY STYLE #1

SHELL FINISH
A = CADMIUM
B = NICKEL
C = ANODIZE
D = CHEM FILM
E = BLACK CADMIUM
G = GOLD
P = PASSIVATION (STAINLESS STEEL)

TERMINATIONS
1 = .109 ± .015
2 = .140 ± .015
3 = .172 ± .015
4 = .190 ± .015
5 = .250 ± .015
6 = .125 ± .015
7 = .375 ± .015
8 = .500 ± .015

ALL 24 AWG (.020 DIA)
HOT SOLDER DIPPED

THREADED INSERT BODY STYLE #2
(OMIT IF NOT USED)
#2-56 FOR SIZES 9-69
#4-40 FOR SIZE 100

MATERIALS AND FINISHES ARE IAW MIL-DTL-83513
FOR DETAILS SEE MIL SPEC OR WWW.CRISTEK.COM

1. MATERIALS:
SHELL - ALUMINUM ALLOY OR STAINLESS STEEL
INSULATOR/BACKSHELL - GLASS FILLED THERMOPLASTIC
PIN/SOCKET CONTACT - COPPER ALLOY
INTERFACIAL SEAL - FLUOROSILICONE BLEND

2. FINISH:
SHELL - SEE OPTIONS ABOVE
PIN/SOCKET CONTACT - GOLD OVER NICKEL

3. SPECIFICATIONS:
CURRENT RATING -------------- 3 AMPS MAX
TEMPERATURE RATING --------- -55° C TO +125° C
INSULATION RESISTANCE ------ 5000 MEGOHMS MIN
DWP AT SEA LEVEL ------------ 600 VAC
DWP AT 70,000 FT ALTITUDE --- 150 VAC
CONTACT RESISTANCE --------- 24 AWG = 25 MIILOHMS MAX.
CONTACT RETENTION ----------- 5 lb MINIMUM AXIAL LOAD
ENGAGEMENT FORCE ----------- 6 oz MAX
SEPARATION FORCE ----------- 0.5 oz MIN

4. ADDITIONAL INFORMATION:
DESIGN AND PERFORMANCE IN GENERAL
ACCORDANCE WITH M83513 WHERE APPLICABLE.
CONTACT CRISTEK FOR RUHS AND OTHER
CONFIGURATIONS.

TOLERANCE: .XXX ± .005
.XX ± .01
ANGLE ± 1°

CRISTEK.COM 888.265.9162
9 CONTACTS

15 CONTACTS

21 CONTACTS

25 CONTACTS

31 CONTACTS

37 CONTACTS

51 CONTACTS

69 CONTACTS

100 CONTACTS

MBC RECEPTACLE PCB LAYOUTS

* SIZES 9-37: 0.100 X 0.075 GRID PATTERN OFFSET BY 0.050
** SIZES 51-100: 0.075 X 0.075 GRID PATTERN OFFSET BY 0.0375